800mA Fully Integrated Linear Charger for 1Cell Li-ion Battery with VINDPM

1 Descriptions

The SC70562x is a highly integrated linear charger for 1cell Li-ion battery applications. It supports up to 800mA charging current and provides battery charge management functions including trickle charge, constant current charge, constant voltage charge, charge termination and charging status indication.

No external sense resistor is needed, and no blocking diode is required. Furthermore, the SC70562x is specifically designed to work with in USB power specifications. Its low external component count makes the SC70562x ideally suited for portable applications. Thermal feedback regulates the charge current to limit their temperature during high power operation or high ambient temperature. The charge current can be programmed externally with a single resistor. The SC70562x automatically terminates the charge cycle when the charge current drops to 1/10th of the programmed value after the final float voltage is reached. When the input supply (wall adapter or USB supply) is removed, the SC70562x automatically enters a low power sleep mode, dropping the battery drain current to less than 0.25µA. The SC70562x can be put into shutdown mode, also reducing the supply current to 0.25µA .Other features include battery pack temperature monitor, under voltage lockout, battery reserve insert protection, automatic recharge and two status pins to indicate charging and charge termination.

The SC70562x also supports input voltage limit (VINDPM). When input source is over-loaded, the input voltage falls below the input voltage limit (VINDPM). The device then reduces the charge current until the input voltage rises above the input voltage limit.

SC70562x is available in DFN2X2-8 package.

3 Applications

- Bluetooth Application
- Toys
- Portable Media Players

2 Features

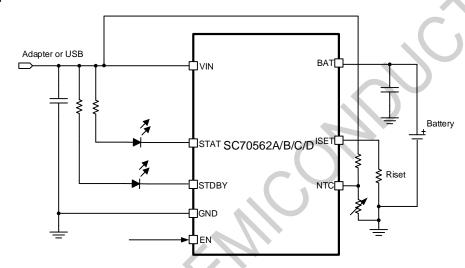
- 26.5V Maximum Input Voltage Rating with Vin Over-Voltage Protection
- Integrated Linear Charger for Single-Cell Battery directly from USB or AC Adapter
- 2.9V TC to CC Threshold
- ±1% Accuracy for VBAT Target Voltage:
 4.2V,4.35V,4.4V,4.45V
- Charging Management: Trickle Charge/Constant Current Charge/Constant Voltage Charge/Charge Termination/Auto Recharge
- Charge Current up to 800mA
- 4.45V Fixed Input Voltage Limit(VINDPM)
- NTC for Battery Protection
- Battery Reserve Insert Protection
- ISET Short Protection
- Input Under Voltage and Over Voltage Protection
- Thermal Regulation and Thermal Shutdown
- Soft-Start Limits Inrush Current
- Chip Enable Control



4 Device Information

ORDER NUMBER	PARAMETER V _{BAT_REG}	PACKAGE	BODY SIZE
SC70562ADDFR	4.2V	DFN2X2-8	2mm x 2mm x 0.75mm
SC70562BDDFR	4.35V	DFN2X2-8	2mm x 2mm x 0.75mm
SC70562CDDFR	4.4V	DFN2X2-8	2mm x 2mm x 0.75mm
SC70562DDDFR	4.45V	DFN2X2-8	2mm x 2mm x 0.75mm

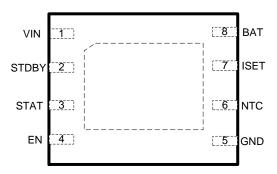
5 Typical Application Circuit





6 Terminal Configuration and Functions

TOP VIEW (DFN2X2-8)



TERMINAL			DESCRIPTION
NUMBER	NAME	I/O	
1	VIN	1	Charger Input Supply. Needs to be bypassed with a MLCC capacitor.
2	STDBY	0	Open-Drain Charge Status Output. The STDBY pin outputs low when the battery is finished charging. When the charger is in charging mode, it becomes high-impendence.
3	STAT	0	Open-Drain Charge Status Output. The STAT pin outputs low when the battery is charging. Upon the completion of the charge cycle, it becomes high-impendence.
4	EN	ı	Chip enable pin. A high input will put the device in the normal operating mode. Pulling the EN pin to low level will put the device into disable mode. If connecting EN to VIN, the user must add a resistor between VIN and EN to ensure EN pin is safe when VIN higher than 6V. EN has an internal $600~k\Omega$ pull up resistor.
5	GND	I/O	Ground Pin.
6	NTC	ı	Connect to the Negative Temperature Coefficient (NTC) thermistor inside the battery cells to sense the battery cells temperature for protection. Short NTC pin to GND to disable the NTC function.
			Program the charge current and Shutdown. This pin set to 1V in constant-current charge mode. The charge current is programmed by connecting a 1% resistor (R _{ISET}), between ISET, to GND pin. The charge current can be calculated using the following formula:
7	ISET	1	I _{CC} =1000/ R _{ISET}
			Where R _{ISET} is the resistor between the ISET pin to GND.
			The ISET pin can also be used to switch the charger to shutdown mode by disconnecting the program resistor from ground.
8	BAT	0	Charger current output pin. Bypass BAT to GND with a MLCC capacitor.

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	Unit
	VIN	-0.3	26.5	٧
Voltage range at terminals ⁽²⁾	BAT	-8	8	\ \
terrimidie	ISET, STAT, STDBY, EN, NTC	-0.3	6	٧
T _J	Operating junction range	-40	150	°C
T _{stg}	Storage temperature range	-65	150	°C

⁽¹⁾ Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 Handling Ratings

PARAMETER	DEFINITION		MAX	UNIT
ESD ⁽¹⁾	Human body model (HBM) ESD stress voltage ⁽²⁾ All pins	-2	2	kV
ESD	Charged device model (CDM) ESD stress voltage ⁽³⁾	-1	1	kV

⁽¹⁾ Electrostatic discharge (ESD) to measure device sensitivity and immunity to damage caused by assembly line electrostatic discharges into the device.

7.3 Recommended Operating Conditions

		MIN	TYP	MAX	UNIT
Vin	Input voltage range(USB Input)	4.5	5	6	V
I _{BAT_CHG}	MAX BAT charge constant current		800		mA
	VBAT regulation voltage(SC70562A)		4.2		٧
	VBAT regulation voltage(SC70562B)		4.35		V
VBAT_REG	VBAT regulation voltage(SC70562C)		4.4		V
	VBAT regulation voltage(SC70562D)		4.45		V
TA	Operating ambient temperature	-40		85	°C
TJ	Operating junction temperature	-40		125	°C

⁽²⁾ All voltage values are with respect to network ground terminal.

⁽²⁾ Level listed above is the passing level per ANSI, ESDA, and JEDEC JS-001. JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

⁽³⁾ Level listed above is the passing level per EIA-JEDEC JESD22-C101. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



7.4 Thermal Information

(4) THERMAL	RESISTANCE ⁽¹⁾		Unit
θ_{JA}	Junction to ambient thermal resistance	118	°C/W
θ _{JC}	Junction to case resistance	25	°C/W

Measured on JESD51-7, 4-layer PCB.

7.5 Electrical Characteristics

 T_A = 25°C and V_{IN} = 5V, V_{BAT} = 3.5V unless otherwise noted.

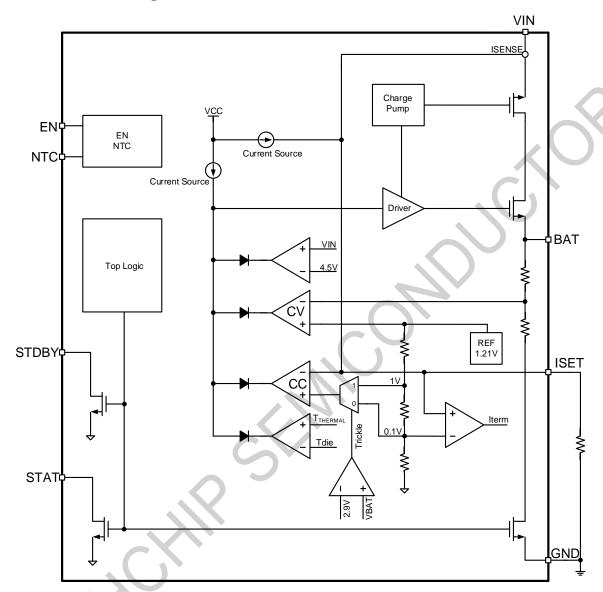
PARAMET	ER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY V	OLTAGE and Battery Protection			11	7	
V _{IN}	Operating input voltage		4.5	5	6	V
	V _{IN} under-voltage lockout	Rising edge	3.55	3.8	4.1	V
V _{IN_UVLO}	threshold	Hysteresis		500		mV
\ /	V _{IN} over-voltage protection	Rising edge	6.5	6.7	7	V
V_{IN_OVP}	threshold	Hysteresis		200		mV
	V _{IN} - V _{BAT} under-voltage lockout	Rising edge		100		mV
VSLEEP	threshold	Hysteresis		70		mV
I _{IN}	V., Supply current	Standby Mode (After EOC)		100		μΑ
I _{IN} V _{IN} Supply current	V _{IN} Supply current	Shutdown Mode (ISET Floating, EN Low, VIN <v<sub>BAT, V_{IN}<v<sub>IN_UVLO)</v<sub></v<sub>		40		μΑ
		Standby Mode (After EOC), V _{BAT} =4.2V		2		μΑ
BAT Pin current	BAT Pin current	Shutdown Mode (ISET Floating, EN Low, VIN <v<sub>BAT, V_{IN}<v<sub>IN_UVLO)</v<sub></v<sub>		250	350	nA
		Sleep Mode (V _{IN} =0V)		250	350	nA
Power						
Ron	RDSON resistance of MOSFET			600		mΩ
Battery Ch	arger Management					
		SC70562A	4.158	4.2	4.242	V
		SC70562B	4.306	4.35	4.393	V
VBAT	BAT regulated voltage	SC70562C	4.356	4.4	4.444	V
		SC70562D	4.361	4.45	4.539	V
lcc		R_{ISET} =20kΩ, CC Mode	44	50	56	mA
	Constant charge current	R _{ISET} =10kΩ, CC Mode	94	100	106	mA
100	Constant only outrent	R_{ISET} =2k Ω , CC Mode	470	500	530	mA
		R _{ISET} =1.25kΩ, CC Mode	728	800	872	mA



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ITC	Trickle change current			0.1*Icc		
I _{TERM}	0.1*I _{CC} charge termination current		0.085	0.1	0.115	mA/mA
T _{TERM_DGL}	Termination deglitch time			1		s
V	Trickle charge to constant current	VBAT rising	2.8	2.9	3	V
V _{BAT_TC}	charge threshold	Hysteresis		130		mV
V _{RECH}	Battery auto-recharge voltage	V _{BAT_REG} -V _{BAT}		120		mV
T _{RECH_DGL}	Battery auto-recharge deglitch time			0.5		S
V _{I_SET}	I _{SET} PIN voltage	CC Mode		1		V
I _{I_SET}	I _{SET} PIN pull up current			3		μΑ
T _{SS}	Soft start time	I _{BAT} from 0A to I _{CC}		100		μs
Vstat_low	STAT or STDBY output Low voltage	I _{STAT} or I _{STDBY} 5mA Current			0.6	V
VINDPM						
VINDPM	Input Voltage limit			4.45		V
Thermal Pr	rotection)			
T_{J_SD}	Thermal shutdown temperature			150		°C
I J_SD	Thermal shutdown hysteresis			20		°C
T_{J_REG}	Thermal regulation temperature			120		°C
V_{DISNTC}	NTC disable threshold As a percentage of V _{IN}			5		%
\ /	NTC cold temperature threshold	Rising		80	83	%
V _{COLD}	As a percentage of V _{IN}	Hysteresis(Falling)		2		%
V_{HOT}	NTC hot temperature threshold	Falling	42	45		%
V HOT	As a percentage of V _{IN}	Hysteresis(Rising)		2		%
Logic I/O P	Pin		•			•
VIL	EN Low logic voltage threshold				0.4	V
VIH	EN High logic voltage threshold		1.3			V

8 Functional Block Diagram



9 Feature Description

9.1 Operation

The SC70562x is a single cell lithium-ion battery charger using a constant-current/constant-voltage algorithm. It can deliver up to 800mA of charge current (using a good thermal PCB layout) with a final float voltage accuracy of $\pm 0.8\%$. The SC70562x includes an internal power MOSFET and thermal regulation circuitry. No blocking diode or external current sense resistor is required.

9.2 Input OVP and UVLO

The SC70562x has an input over-voltage protection (VIN _OVP) and an input UVLO threshold. Once the input voltage is out of its normal range, the charger is turned off immediately.

An internal under voltage lockout circuit monitors the input voltage and keeps the charger in shutdown mode until VIN rises above the under voltage lockout threshold. The UVLO circuit has a built-in hysteresis of 500mV.

9.3 Battery Charge Management

The SC70562x provides charge management functions for 1 cell Li-ion battery. The typical charge profile is shown in Figure 1.

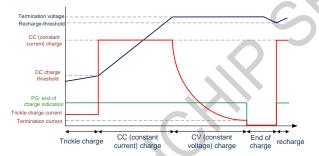


Figure 1 Typical Charge Profile

9.3.1 Trickle Charge

When VBAT is lower than 2.8V, the SC70562x charges the battery cells in trickle charge mode(TC). The trickle charge current is 1/10 of setting I_{CC} Current.

9.3.2 Constant Current Charge

When VBAT voltage is charged above 2.9V, the SC70562x enters into constant current charge (CC) mode. The constant current can be programmed via:

Icc=1000/ RISET

Where RISET is the resistor between the ISET pin to GND.

Recommended R_{ISET} value is from $20k\Omega$ to $1.25k\Omega$, related ICC from 50mA to 800mA, however, if the PCB thermal performance is good enough, this IC can support 1A charge current with $1k\Omega$ R_{ISET}.

9.3.3 Constant Voltage Charge

When the battery voltage rises to 4.2V(SC70562A)/ 4.35V(SC70562B) / 4.4V(SC70562C) / 4.45V(SC70562D), the charge mode changes from CC mode to CV mode. In CV mode, the battery voltage is regulated at V_{BAT_REG} . The charge current automatically drops.

9.3.4 Charge Termination Current

ITERM=100/RISET

Where R_{SET} is the resistor between the ISET pin to GND.

9.3.5 Charge Termination/End of Charge

A charge cycle is terminated when the charge current falls to the charge termination current after the final float voltage is reached. This condition is detected by using an internal, filtered comparator to monitor the ISET pin. When the ISET pin voltage falls below 100mV for longer than t_{TERM} (typically 1s), charging is terminated. The charge current is latched off and the SC70562x enters standby mode, where the input supply current drops to 100 μ A. In this state, all loads on the BAT pin must be supplied by the battery.

A new charge cycle starts when any of the following conditions are valid:

- The input power is recycled.
- Auto-recharge kicks in.
- Pull EN low then to High
- Reconnecting the ISET resistor.

Under the following condition:

No thermistor fault at NTC Cold and Hot.

9.3.6 Auto Recharge

When the battery is fully charged and charging is terminated, the battery may be discharged due to system consumption or self-discharge. When the battery voltage is discharged below the recharge threshold and VIN is still in the operating range, the SC70562x begins another new charging cycle automatically without having to restart a charging cycle manually.

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9.4 Charge Status indicator

Charge Status	STAT	STDBY
Charging	Low	HI-Z
Charge Termination	HI-Z	Low
V _{IN} UVLO, V _{IN} OVP, V _{IN} Sleep, V _{IN} Removed	HI-Z	HI-Z
Shutdown mode (EN Low or float ISET Pin)	HI-Z	HI-Z
NTC Fault	HI-Z	HI-Z

Table 1 STAT and STDBY Status

9.5 Manual Shut down

There are two methods to manual shut down the charger:

- 1. Pull EN to be low.
- 2. Float the ISET pin by removing the resistor from ISET pin to GND.

Once one of above conditions occurs can put the charger into shutdown mode. The battery drain current reduced to be 250nA and supply current to be 40uA. Reconnecting the ISET resistor or pull EN High to will start a new charger cycle.

9.6 NTC

The SC70562x monitors the battery cell temperature through NTC pin once V_{IN} is above UVLO threshold. It compares NTC pin voltage with VIN voltage. Once it detects the NTC pin voltage is below V_{HOT} or higher than V_{COLD} , the IC transitions to shutdown mode. SC70562x will resume to normal operation after the NTC pin voltage back to normal. NTC function can be also disabled through shorting the pin to GND.

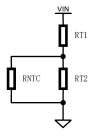


Figure 2 NTC Operation

Use below equations to calculate the RT1/RT2 resistance when a NTC thermistor is used as shown in Figure 2.

$$R_{\text{T2}} = \frac{R_{\text{COLD}} \times R_{\text{HOT}} \times (\frac{1}{V_{\text{COLD}}} - \frac{1}{V_{\text{HOT}}})}{R_{\text{HOT}} \times (\frac{1}{V_{\text{HOT}}} - 1) - R_{\text{COLD}} \times (\frac{1}{V_{\text{COLD}}} - 1)}$$

$$R_{TI} = \frac{\frac{1}{V_{COLD}} - 1}{\frac{1}{R_{TD}} + \frac{1}{R_{COLD}}}$$

Where, R_{HOT} is the NTC resistance at the hot temperature threshold, R_{COLD} is the resistance at the cold threshold.

9.7 Thermal Regulation and Shut Down

An internal thermal feedback loop reduces the programmed charge current if the die temperature attempts to rise above a preset value of approximately 120°C. This feature protects the SC70562x from excessive temperature and allows the user to push the limits of the power handling capability of a given circuit board without risk of damaging the SC70562x. The charge current can be set according to typical (not worst-case) ambient temperature with the assurance that the charger will automatically reduce the current in worst-case conditions.

Once the die temperature reach to 150°C, the chip enters into shutdown mode, after the temperature back to 130°C, the chip recover normal mode.

9.8 VINDPM

The SC70562x also supports input voltage limit (typical 4.45V). When input source is over-loaded, the input voltage falls below the input voltage limit (VINDPM). The device then reduces the charge current until the input voltage rises above the input voltage limit.

9.9 ISET Short Protection

After Vin power up and /EN is low, SC70562x will have a ISET short detection. When the ISET short is detected, the charge current will be clamped and latched to about 850mA.

A new ISET short detection cycle starts when any of the following conditions are valid:

- The input power is recycled.
- Pull EN low to high.

10 Application Information

10.1 Input Capacitor Selection

Typically, a $1\mu F$ X5R ceramic capacitor should be sufficient to suppress the power supply noise.

10.2 Output Capacitor Selection

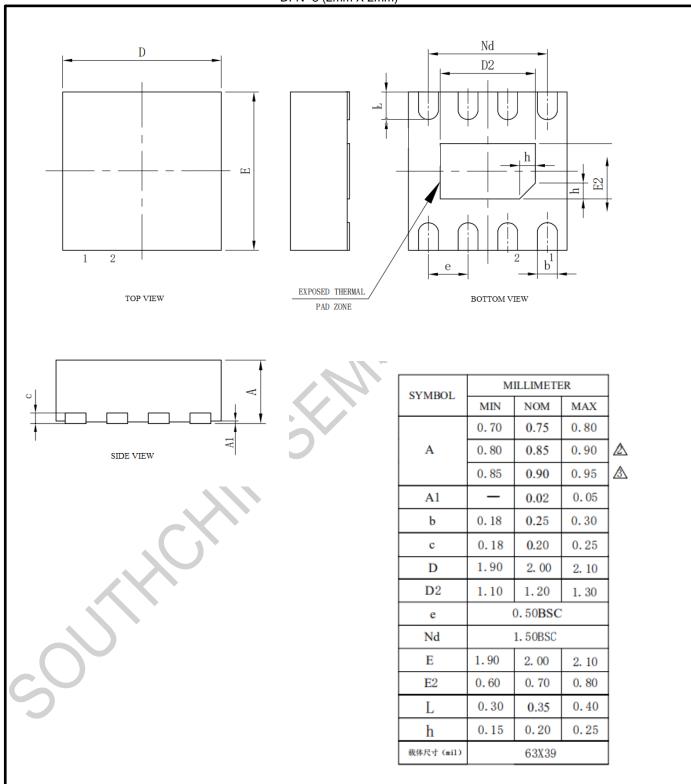
Typically, a $1\mu F$ X5R ceramic capacitor to maintain the stability of the charger as well as to bypass any transient load current.

10.3 Layout Guideline

The SC70562x uses DFN package which has an exposed thermal pad at the bottom side of the package. The layout should connect as much as possible to copper on the exposed pad. Typically the component layer is more effective in dissipating heat. The thermal impedance can be further reduced by using other layers of copper connecting to the exposed pad through a thermal via array.

MECHANICAL DATA

DFN -8 (2mm X 2mm)



RECOMMENDED FOOTPRINT(Unit mm) 1.95 5 0.6

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